## **CLAIMS**

- 1 1. A magnetic head comprising:
- a write head portion including a first magnetic pole and a second magnetic pole;
- an induction coil being disposed at least in part between said first and second
- 4 magnetic poles;
- 5 an electrical lead of said induction coil being disposed in a layer of the magnetic
- 6 head;
- 7 a heat sink being coplanar within the magnetic head with said electrical lead of
- 8 said coil.
- 1 2. A magnetic head as described in claim 1 wherein said electrical lead is comprised
- 2 of copper and said heat sink is comprised of copper.
- 1 3. A magnetic head as described in claim 1 wherein said heat sink is disposed at
- 2 least in part upon said second magnetic pole.
- 1 4. A magnetic head as described in claim 1 wherein said electrical lead is fabricated
- 2 upon an insulation layer that is disposed in part above said second magnetic pole, and
- 3 wherein said heat sink is fabricated upon said insulation layer above said second
- 4 magnetic pole.

- 1 5. A magnetic head as described in claim 4 wherein said heat sink includes a first
- 2 substantial portion that is disposed above said second magnetic pole, and another
- 3 substantial portion that is disposed away from said second magnetic pole.
- 1 6. A magnetic head as described in claim 5 wherein said heat sink is disposed away
- 2 from an air bearing surface of the magnetic head.
- 1 7. A magnetic head as described in claim 1 further including a second heat sink, and
- 2 wherein said heat sink and said second heat sink are thermally interconnected by a heat
- 3 sink interconnect member.
- 1 8. A magnetic head as described in claim 7 wherein said second heat sink is
- 2 disposed below said first magnetic pole.
- 1 9. A magnetic head as described in claim 8 wherein said heat sink is thermally
- 2 interconnected through an interconnect member with a slider body portion of the
- 3 magnetic head.
- 1 10. A magnetic head as described in claim 8 wherein said heat sink is thermally
- 2 interconnected with said second heat sink through an interconnect member, and said
- 3 second heat sink is thermally interconnected with said slider body through a second
- 4 interconnect member.

- 1 11. A magnetic head as described in claim 1 wherein said magnetic head is a
- 2 longitudinal head.
- 1 12. A magnetic head as described in claim 1 wherein said magnetic head is a
- 2 perpendicular magnetic head.
- 3 13. A method for fabricating a magnetic head, comprising:
- 4 fabricating a first magnetic pole;
- 5 fabricating a second magnetic pole;
- fabricating an induction coil, at least in part, between said first magnetic pole and
- 7 said second magnetic pole;
- 8 fabricating an electrical lead to said induction coil;
- 9 fabricating a heat sink member in the same fabrication step in which said
- 10 electrical lead is fabricated.
- 1 14. A method for fabricating a magnetic head as described in claim 13, comprising:
- 2 fabricating said heat sink in a location above said second magnetic pole.
- 1 15. A method for fabricating a magnetic head as described in claim 13 wherein said
- 2 electrical lead and said heat sink are fabricated in a photolithographic process.
- 1 16. A method for fabricating a magnetic head as described in claim 15 wherein said
- 2 photolithographic process includes the use of a mask for forming an electrical lead

- 3 electroplating trench, and said mask also includes an opening for forming a heat sink
- 4 trench for electroplating said heat sink therewithin.
- 1 17. A method for fabricating a magnetic head as described in claim 13 wherein said
- 2 heat sink includes a first portion that is disposed above said second magnetic pole and a
- 3 second portion that is disposed away from said second magnetic pole.
- 1 18. A method for fabricating a magnetic head as described in claim 13, including the
- 2 step of fabricating a second heat sink that is disposed below said first magnetic pole.
- 1 19. A method for fabricating a magnetic head as described in claim 18, including the
- 2 step of fabricating a thermal interconnect member between said first heat sink and said
- 3 second heat sink.
- 1 20. A method for fabricating a magnetic head as described in claim 19, including the
- 2 further step of fabricating a thermal interconnect member between said second heat sink
- 3 and a slider body portion of the magnetic head.
- 4 21. A hard disk drive, comprising:
- 5 at least one hard disk being adapted for rotary motion upon a disk drive;
- at least one slider device having a slider body portion being adapted to fly over
- 7 said hard disk;

- 8 a magnetic head being formed on said slider body for writing data to said hard
- 9 disk, said magnetic head including:
- a write head portion including a first magnetic pole and a second magnetic pole;
- an induction coil being disposed at least in part between said first and second
- magnetic poles;
- an electrical lead of said induction coil being disposed in a layer of the magnetic
- 14 head;
- a heat sink being coplanar within the magnetic head with said electrical lead of
- 16 said coil.
- 1 22. A hard disk drive as described in claim 21 wherein said heat sink is disposed at
- 2 least in part upon said second magnetic pole.
- 1 23. A hard disk drive as described in claim 21 wherein said electrical lead is
- 2 fabricated upon an insulation layer that is disposed in part above said second magnetic
- 3 pole, and wherein said heat sink is fabricated upon said insulation layer above said
- 4 second magnetic pole.
- 1 24. A hard disk drive as described in claim 21 further including a second heat sink,
- 2 and wherein said heat sink and said second heat sink are thermally interconnected by a
- 3 heat sink interconnect member.

- 1 25. A hard disk drive as described in claim 24 wherein said second heat sink is
- 2 disposed below said first magnetic pole.
- 1 26. A hard disk drive as described in claim 25 wherein said heat sink is thermally
- 2 interconnected through an interconnect member with a slider body portion of the
- 3 magnetic head.
- 1 27. A hard disk drive as described in claim 25 wherein said heat sink is thermally
- 2 interconnected with said second heat sink through an interconnect member, and said
- 3 second heat sink is thermally interconnected with said slider body through a second
- 4 interconnect member.